

Material Declaration Sheet

MLCC Sub-Division

Part / Product Paining Details		· · · · · · · · · · · · · · · · · · ·							
	Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mmm-yyyy	Total product Weight (mg)	Value Range	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used	
I	VJ0603Y223KXBA	YES	1-Jan-1996	6.43245	22000	Yes	Israel	None	

Technical Information						
Terminal Plating / Grid Array		JESD-97 Pb-Free Material		Reflow	Reflow	Reflow
Material	Terminal Base Alloy	Code Marking	J-STD-20D MSL Rating	Peak Process	Maximum	Max.Time at Pea

Material Composition								
Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
		4		(mg)	%	ppm	Total i roduct weight	
Dielectric X7R - High K (Lead-free)				5.17600				
	Ceramic	Barium Titanium Trioxide	12047-27-7	5.02072	97.00	970000	78.05	0 - None
	_	Misc.	-	0.15528	3.00	30000	2.41	0 - None
Electrode		·	·	0.24400				
	Conductive paste	Palladium	5/3/7440	0.07320	30.00	300000	1.14	0 - None
		Silver	7440-22-4	0.17080	70.00	700000	2.66	0 - None
Plating		·	·	0.35245				
	Plating	Nickel	7440-02-0	0.11795	33.47	334657	1.83	0 - None
		Tin	7440-31-5	0.23450	66.53	665343	3.65	0 - None
Termination		•		0.66000			·	•
	Conductive paste	Silver	7440-22-4	0.63360	96.00	960000	9.85	0 - None
		Misc.	-	0.02640	4.00	40000	0.41	0 - None

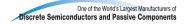
EU-RoHS Directive-2011/65/EU MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium

Exemption Used NONE

Note: - (i) All information is based on data received from our vendors & subjected to change without prior notice.

(ii) Substance weight are derived from MSDS.





11/30/2013

Soldering Compatibility (SnPb/Pb-Free)

Backward & Forward